MP7626

Microprocessor Compatible Buffered Multiplying 16-Bit Digital-to-Analog Converter

FEATURES C

• Four Quadrant Multiplication

X EXA

- 16-Bit Monotonicity
- Low Power Consumption
- TTL/5 V CMOS Compatible
- Single-Buffered or Transparent Data inputs
- Decoded DAC Approach
- Latch-Up Free
- 8-Bit Bus Version: MP7636A

APPLICATIONS

- Digitally Programmable References
- Programmable Audio Attenuator
- High Accuracy Process Control Systems
- Automatic Test Equipment
- Easy Interface to 8 and 16-Bit Microprocessor Buses

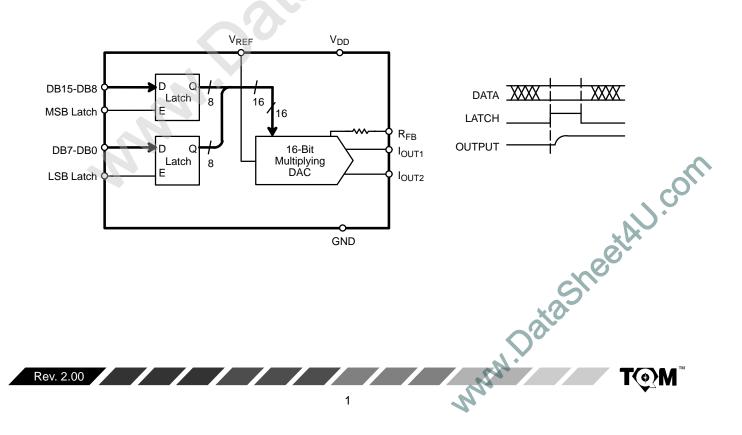
GENERAL DESCRIPTION

The MP7626 is a CMOS 16-bit Digital-to-Analog Converter (DAC) that is manufactured using advanced thin film resistors on a double metal CMOS process. It incorporates a unique bit decoding technique yielding lower glitch, higher speed and

excellent accuracy over temperature and time. 16 bit differential non-linearity is achieved with minimal trimming.

Two 8-bit latches (MSB latch and LSB latch) hold the 16-bit data which are converted by the DAC. A 16-bit bus can load both latches in one cycle. An 8-bit bus loads one latch at a time. By making the latches transparent (MSB latch = LSB latch = High) the DAC will continuously convert the BIT1 - BIT16 inputs.

SIMPLIFIED BLOCK AND TIMING DIAGRAM



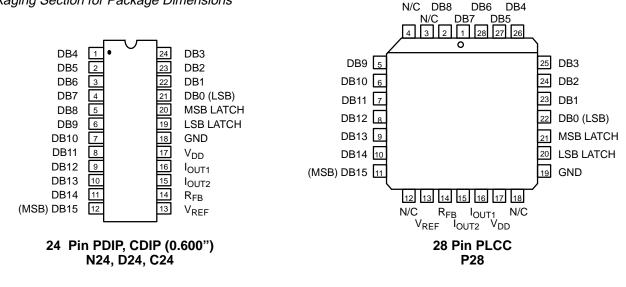
ORDERING INFORMATION

Package Type	Temperature Range	Part No.	INL (LSB)	DNL (LSB)	Gain Error (% FSR)
Plastic Dip	–40 to +85°C	MP7626JN	<u>+</u> 4	<u>+</u> 4	<u>+</u> 0.1
Plastic Dip	–40 to +85°C	MP7626KN	<u>+</u> 2	<u>+</u> 2	<u>+</u> 0.1
PLCC	–40 to +85°C	MP7626JP	<u>+</u> 4	<u>+</u> 4	<u>+</u> 0.1
PLCC	–40 to +85°C	MP7626KP	<u>+</u> 2	<u>+</u> 2	<u>+</u> 0.1
Ceramic Dip	–40 to +85°C	MP7626JD*	<u>+</u> 4	<u>+</u> 4	<u>+</u> 0.1
Ceramic Dip	–40 to +85°C	MP7626KD*	<u>+</u> 2	<u>+</u> 2	<u>+</u> 0.1

*Recommend using MP7626KN or JN

PIN CONFIGURATION

See Packaging Section for Package Dimensions



PIN OUT DEFINITIONS

DIP	PLCC	NAME	DESCRIPTION	DIP	PLCC	NAME	DESCRIPTION
1	26	DB4	Data Input Bit 4	13	13	V _{REF}	Reference Input Voltage
2	27	DB5	Data Input Bit 5	14	14	R _{FB}	Internal Feedback Resistor Pin
3	28	DB6	Data Input Bit 6	15	15	I _{OUT2}	Current Output 2
4	1	DB7	Data Input Bit 7	16	16	I _{OUT1}	Current Output 1
5	2	DB8	Data Input Bit 8	17	17	V _{DD}	Power Supply
6	5	DB9	Data Input Bit 9	18	19	GND	Ground
7	6	DB10	Data Input Bit 10	19	20	LSB	LSB Latch Enable
8	7	DB11	Data Input Bit 11	20	21	MSB	MSB Latch Enable
9	8	DB12	Data Input Bit 12	21	22	DB0	Data Input Bit 0 (LSB)
10	9	DB13	Data Input Bit 13	22	23	DB1	Data Input Bit 1
11	10	DB14	Data Input Bit 14	23	24	DB2	Data Input Bit 2
12	11	DB15	Data Input Bit 15 (MSB)	24	25	DB3	Data Input Bit 3





ELECTRICAL CHARACTERISTICS

(VDD = + 15 V, VREF = +10 V unless otherwise noted)

Parameter	Symbol	Min	25 [°] С Тур	Max	Tmin to Min	Tmax Max	Units	Test Conditions/Comments
STATIC PERFORMANCE ¹								FSR = Full Scale Range
Resolution (All Grades)	N	16			16		Bits	
Relative Accuracy J K	INL			<u>+</u> 4 <u>+</u> 2		<u>+</u> 4 <u>+</u> 2	LSB	Best Fit Straight Line Spec. (Max INL – Min INL) / 2
Differential Non-Linearity J K	DNL			<u>+</u> 4 <u>+</u> 2		<u>+</u> 4 <u>+</u> 2	LSB	
Gain Error	GE			<u>+</u> 0.1		<u>+</u> 0.1	% FSR	Using Internal R _{FB}
Gain Temperature Coefficient ²	TC _{GE}					<u>+</u> 2	ppm/°C	∆Gain/∆Temperature
Power Supply Rejection Ratio	PSRR			<u>+</u> 50		<u>+</u> 50	ppm/%	$ \Delta Gain/\Delta V_{DD} \Delta V_{DD} = \pm 5\%$
Output Leakage Current	Ι _{ΟυΤ}			<u>+</u> 10		<u>+</u> 200	nA	I _{OUT1}
DYNAMIC PERFORMANCE ²								R _L =100Ω, C _L =13pF
Current Settling Time AC Feedthrough at I _{OUT1}	ts F _T		2 2				μs mV p-p	Full Scale Change to 0.1% V _{REF} = 10kHz, 20 Vp-p, sinewave
REFERENCE INPUT								
Input Resistance	R _{IN}	2.5		7.5	2.5	7.5	kΩ	
DIGITAL INPUTS ³								
Logical "1" Voltage Logical "0" Voltage Input Leakage Current Input Capacitance ² Data Control	V _{IH} V _{IL} I _{LKG} C _{IN}	3.0	2.4 5 5	0.8 <u>+</u> 1	3.0	0.8 <u>+</u> 1	V V μA pF pF	
ANALOG OUTPUTS ²								
Output Capacitance	Cout1 Cout1 Cout2 Cout2			280 120 100 240			pF pF pF pF	DAC Inputs all 1's DAC Inputs all 0's DAC Inputs all 1's DAC Inputs all 0's
POWER SUPPLY								
Functional Voltage Range ⁵ Supply Current	V _{DD} I _{DD}	4.5		16.5 1	5.0	16.5 1	V mA	All digital inputs = 0 V or all = 5 V





ELECTRICAL CHARACTERISTICS (CON'T)

Parameter	Symbol	Min	25°C Typ	Max	Tmin to Min	o Tmax Max	Units	Test Conditions/Comments
SWITCHING CHARACTERISTICS ^{2, 4}								
Data Valid to Write Set-Up Time Write Strobe Width	t _{DS} t _{SW}	250 125					ns ns	

NOTES:

- ¹ Full Scale Range (FSR) is 10V for unipolar mode.
- ² Guaranteed but not production tested.
- ³ Digital input levels should not go below ground or exceed the positive supply voltage, otherwise damage may occur.
- ⁴ See timing diagram.
- ⁵ Specified values guarantee functionality. Refer to other parameters for accuracy.

Specifications are subject to change without notice

ABSOLUTE MAXIMUM RATINGS (TA = +25°C unless otherwise noted)^{1, 2}

Supply Voltage	+17 V _{DC}
Voltage at Any Digital Input GND -0.5 to VI	_{DD} +0.5 V
DC Voltage Applied to IOUT1 or IOUT2 GND -0.5	to +17 V
Voltage at V _{REF} , R _{FB} Inputs	<u>+</u> 25 V

Storage Temperature Range –65°C to 150°C	
Package Power Dissipation Rating to 75°C	
CDIP, PDIP, PLCC 1050mW	
Derates above 75°C 14mW/°C	

NOTES:

- Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation at or above this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.
- Any input pin which can see a value outside the absolute maximum ratings should be protected by Schottky diode clamps (HP5082-2835) from input pin to the supplies. *All inputs have protection diodes* which will protect the device from short transients outside the supplies of less than 100mA for less than 100µs.

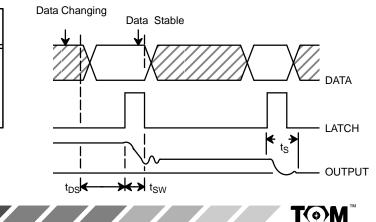
APPLICATION NOTES Refer to Applications Section for Additional Information

LATCH CONTROL

Rev. 2.00

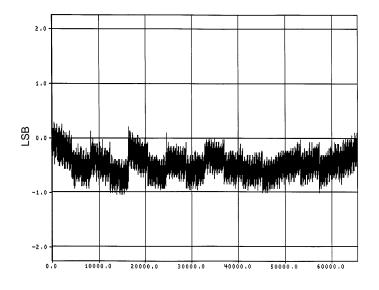
MSB LATCH	LSB LATCH	FUNCTION
0	0	Data Latched (Held)
1	0	Transfer (DB15-DB8) to DAC
0	1	Transfer (DB7-DB0) to DAC
1	1	Transparent Mode

TIMING DIAGRAM





PERFORMANCE CHARACTERISTICS



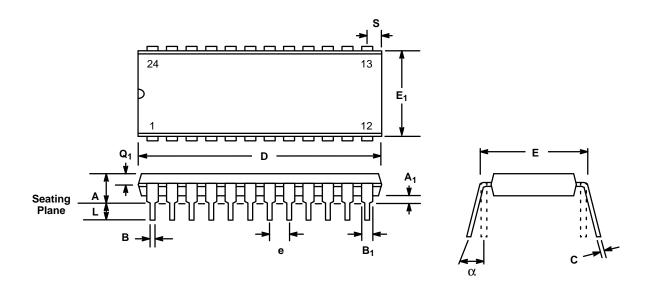
Graph 1. Relative Accuracy vs. Digital Code

APPLICATION NOTES Refer to Section 8 for Applications Information









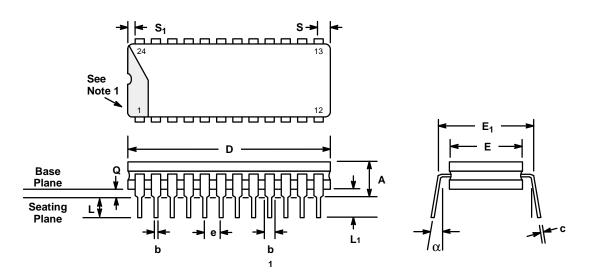
	INC	HES	MILLIN	IETERS
SYMBOL	MIN	MAX	MIN	MAX
А		0.225		5.72
A ₁	0.015	_	0.38	
В	0.014	0.023	0.356	0.584
B ₁ (1)	0.038	0.065	0.965	1.65
С	0.008	0.015	0.203	0.381
D	1.160	1.290	29.46	32.77
E	0.585	0.625	14.86	15.88
E ₁	0.500	0.610	12.70	15.49
е	0.1	00 BSC	2.5	4 BSC
L	0.115	0.150	2.92	3.81
α	0°	15°	0°	15°
Q ₁	0.055	0.070	1.40	1.78
S	0.040	0.098	1.02	2.49

Note: (1) The minimum limit for dimensions B1 may be 0.023" (0.58 mm) for all four corner leads only.





24 LEAD CERAMIC DUAL-IN-LINE (600 MIL CDIP) D24



	INCHES		MILLIN	IETERS	
SYMBOL	MIN	MAX	MIN	MAX	NOTES
А		0.225		5.72	
b	0.014	0.023	0.356	0.584	_
b ₁	0.038	0.065	0.965	1.65	2
С	0.008	0.015	0.203	0.381	_
D		1.290		32.77	4
E	0.500	0.610	12.70	15.49	4
E ₁	0.590	0.620	14.99	15.75	7
е	0.10	DO BSC	2.5	4 BSC	5
L	0.120	0.200	3.05	5.08	_
L ₁	0.150		3.81		—
Q	0.015	0.075	0.381	1.91	3
S		0.098		2.49	6
S ₁	0.005		0.13		6
α	0°	15°	0°	15°	_

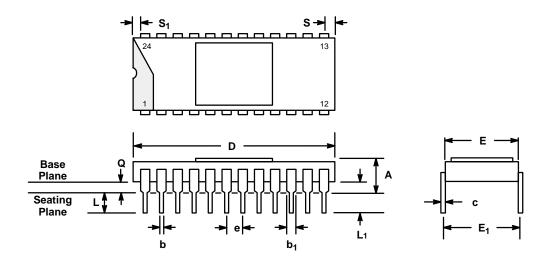
NOTES

- 1. Index area; a notch or a lead one identification mark is located adjacent to lead one and is within the shaded area shown.
- 2. The minimum limit for dimension b_1 may be 0.023 (0.58 mm) for all four corner leads only.
- 3. Dimension Q shall be measured from the seating plane to the base plane.
- 4. This dimension allows for off-center lid, meniscus and glass overrun.
- 5. The basic lead spacing is 0.100 inch (2.54 mm) between centerlines.
- 6. Applies to all four corners.
- 7. This is measured to outside of lead, not center.





24 LEAD CERAMIC SIDE-BRAZED DUAL-IN-LINE (600 MIL S/B DIP) C24



	INCHES		MILLIN	IETERS	
SYMBOL	MIN	MAX	MIN	MAX	NOTES
А	_	0.225		5.72	
b	0.014	0.023	0.356	0.584	—
b ₁	0.038	0.065	0.965	1.65	2
с	0.008	0.015	0.203	0.381	
D	_	1.290		32.77	4
E	0.500	0.610	12.70	15.49	4
E ₁	0.590	0.620	14.99	15.75	7
е	0.10	DO BSC	2.5	4 BSC	5
L	0.120	0.200	3.05	5.08	_
L ₁	0.150	_	3.81		_
Q	0.015	0.075	0.381	1.91	3
S	—	0.098		2.49	6
S ₁	0.005		0.13		6

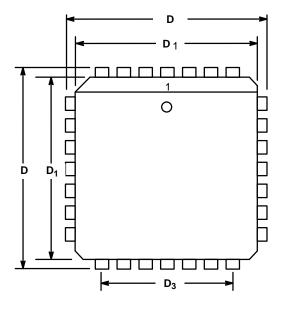
NOTES

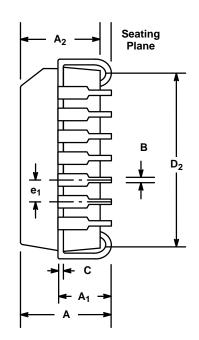
- 1. Index area; a notch or a lead one identification mark is located adjacent to lead one and is within the shaded area shown.
- 2. The minimum limit for dimension b_1 may be 0.023 (0.58 mm) for all four corner leads only.
- 3. Dimension Q shall be measured from the seating plane to the base plane.
- 4. This dimension allows for off-center lid, meniscus and glass overrun.
- 5. The basic lead spacing is 0.100 inch (2.54 mm) between centerlines.
- 6. Applies to all four corners.
- 7. E_1 shall be measured at the centerline of the leads.





28 LEAD PLASTIC LEADED CHIP CARRIER (PLCC) P28





	INC	CHES	MILLI	METERS
SYMBOL	MIN	MAX	MIN	MAX
А	0.165	0.180	4.19	4.57
A ₁	0.100	0.110	2.54	2.79
A ₂	0.148	0.156	3.76	3.96
В	0.013	0.021	0.330	0.533
С	0.008	0.012	0.203	0.305
D	0.485	0.495	12.32	12.57
D ₁ (1)	0.450	0.454	11.43	11.53
D ₂	0.390	0.430	9.91	10.92
D ₃	0.3	00 Ref	7.6	2 Ref.
e ₁	0.0	50 BSC	1.2	7 BSC

Note: (1) Dimension D_1 does not include mold protrusion. Allowed mold protrusion is 0.254 mm/0.010 in.





Notes





Notes





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